

2023 Vietnam Section Report

PART A - SECTION SUMMARY

A.1 Executive Summary

- Section Executive Committee Member List
Chair: Do Hong Tuan
Vice Chair: Huynh Thi Thanh Binh
Secretary: Pham Nguyen Thanh Loan
Treasurer: Huynh Thi Thanh Binh
Student Activities: Tran Minh Triet
- Major Events: 11 events for professional and continuing education activities.
- Major Chapter Activities: organize technical activities, seminars, workshops, conferences for Computational Intelligence Society, Communication Society, Solid-State Circuits Society, Signal Processing Society, Electronics Packaging Society Chapter; connect people in these research fields.

A.2 Financial Report

- Summary (as per submitted on NetSuite)
Opening balance on Jan 2023: 17291.66 USD
Closing balance on Dec 2023: 20058.94 USD
Any other financial activities: receive funding from IEEE R10 only.

PART B - ORGANIZATIONAL ACTIVITIES

B.1 Membership Development Activities

Total number of active members in the past 5 years

Year	2019	2020	2021	2022	2023
Total number of members	188	219	287	307	355

Activities:

IEEE Vietnam section officers meeting at Ho Chi Minh city (in the 2023 IEEE R10 Meeting).

Date: 04 Mar 2023.

Venue: Lotte Hotel Saigon, Ho Chi Minh city, Vietnam.

Reporting the activities in years 2022 and 2023. Discuss for the plan of IEEE Vietnam Section in 2024.

B.2 Chapter Activities

- Total number of Chapters in the Section: 5
- Number of Chapters formed in the current year: 0
- Number of active Chapters (Chapters who have reported required number of meetings during the year): 5.
- Summary of Chapter activities (Chapter wise with attachment table/information):
 1. Electronics Packaging Society (EPS) Chapter Meeting. EPS Malaysia and EPS Vietnam Committee Face-to-Face
Date: 25 August 2023
Venue: Intel Products Vietnam office (Saigon Hi-Tech Park, Lot I2, D1 Road, Phuong Tan Phu, Thu Duc City, HCMC, Vietnam)
https://drive.google.com/drive/folders/13Fdx9Usp7mPuf0AX0uS_yFTPZsu8qeHF?usp=sharing

2. IEEE EPS Vietnam technical day (Electronics Packaging Society Chapter)
Date: 25 August 2023
Venue: Intel Products Vietnam office (Saigon Hi-Tech Park, Lot I2, D1 Road, Phuong Tan Phu, Thu Duc City, HCMC, Vietnam)
Topics: Market and Technology trends of Advanced Packaging, Scientific Writing for Publication, Advanced Semiconductor Packaging for a Smarter World, Career Aspirations in Semiconductor Packaging: Nothing is Impossible!
<https://drive.google.com/drive/folders/19AZOJFRb5Iv3QzYMA4TeHyXhR7spm8QB?usp=sharing>

3. IEEE EPS Vietnam - Tech Day - Technical Sharing
Date: 02 October 2023
Venue: Intel Products Vietnam office (Saigon Hi-Tech Park, Lot I2, D1 Road, Phuong Tan Phu, Thu Duc City, HCMC, Vietnam)
Speaker: Andrew Tay, PhD, Fellow ASME, Fellow IEEE
Topics: Thermomechanical Reliability of Microelectronic Packages
<https://events.vtools.ieee.org/m/377068>

4. Co-organize technical events (Computational Intelligence Chapter)
The 2023 15th International Conference on Knowledge and Systems Engineering (KSE 2023)
Dates: 18-20 October 2023
Venue: Ha Noi, Vietnam.
<https://kse2023.kse-conferences.org/>

5. Technical sponsor (Communication Chapter)
The 2023 International Conference on Advanced Technologies for Communications (ATC 2023)
Dates: 19-20 October 2023
Venue: Da Nang city, Vietnam.
<https://2023.atc-conf.org/>

6. Technical sponsor (Communication Chapter, Computational Intelligence Chapter)
The 2023 International Conference on Computing and Communication Technologies (RIVF 2023)
Dates: 23-25 December 2023
Venue: Ha Noi, Vietnam.
<https://rivf2023.org/>

7. Technical sponsor (Signal Processing Chapter)
The 2023 12th International Conference on Control, Automation and Information Sciences (ICCAIS)
Dates: 27-29 November 2023
Venue: Ha Noi, Vietnam
<http://www.iccais2023.org/>

B.3 Professional and Continuing Education Activities

1. The 2023 15th International Conference on Knowledge and Systems Engineering (KSE 2023)
Dates: 18-20 October 2023
Venue: Ha Noi, Vietnam.
<https://kse2023.kse-conferences.org/>

2. The 2023 International Conference on Advanced Technologies for Communications (ATC 2023)
Dates: 19-20 October 2023
Venue: Da Nang city, Vietnam.
<https://2023.atc-conf.org/>

3. The 2023 International Conference on Computing and Communication Technologies (RIVF 2023)

Dates: 23-25 December 2023

Venue: Ha Noi, Vietnam.

<https://rivf2023.org/>

4. The 2023 12th International Conference on Control, Automation and Information Sciences (ICCAIS)

Dates: 27-29 November 2023

Venue: Ha Noi, Vietnam

<http://www.iccais2023.org/>

5. The 2023 International Conference on Multimedia Analysis and Pattern Recognition (MAPR)

Dates: 05-06 October 2023.

Venue: Quy Nhon, Vietnam.

<https://mapr.uit.edu.vn/2023/>

6. 2023 International Symposium on Electrical and Electronics Engineering (ISEE 2023)

Date: 19-20 October 2023

Venue: Ho Chi Minh city, Vietnam

<https://feee-conf.com/isee2023/>

7. IEEE EPS Vietnam technical day (Electronics Packaging Society Chapter)

Date: 25 August 2023

Venue: Intel Products Vietnam office (Saigon Hi-Tech Park, Lot I2, D1 Road, Phuong Tan Phu, Thu Duc City, HCMC, Vietnam)

Topics: Market and Technology trends of Advanced Packaging, Scientific Writing for Publication, Advanced Semiconductor Packaging for a Smarter World, Career Aspirations in Semiconductor Packaging: Nothing is Impossible!

<https://drive.google.com/drive/folders/19AZOJFRb51v3QzYMA4TeHyXhR7spm8QB?usp=sharing>

8. IEEE EPS Vietnam - Tech Day - Technical Sharing

Date: 02 October 2023

Venue: Intel Products Vietnam office (Saigon Hi-Tech Park, Lot I2, D1 Road, Phuong Tan Phu, Thu Duc City, HCMC, Vietnam)

Speaker: Andrew Tay, PhD, Fellow ASME, Fellow IEEE

Topics: Thermomechanical Reliability of Microelectronic Packages

<https://events.vtools.ieee.org/m/377068>

9. IEEE EPS Distinguished Lecture

Date: 03 October 2023

Venue: Ho Chi Minh City University of Technology, Ho Chi Minh city, Vietnam

Speaker: Andrew Tay, PhD, Fellow ASME, Fellow IEEE

Topics: (1) An Introduction to Microelectronics Packaging, (2) Thermomechanical Reliability of Microelectronic Packages.

<https://drive.google.com/drive/folders/1Xa6nvSoYaaOX-dy53CFXEBikDAxvI1xO?usp=sharing>

10. Summer school “To Be a Future Electrical and Electronics Engineers”: For high-school students, how to be a future Electrical and Electronics Engineers.

Date: 10 June - 08 August 2023

Venue: Ho Chi Minh City University of Technology, Ho Chi Minh city, Vietnam

Participant: 84 high-school students from 22 high schools in Ho Chi Minh city, Dong Nai and Dong Thap provinces. No fees for participants. Studying material for participants is provided.

Instructor: Lecturers and students (as teaching assistants) from Ho Chi Minh City University of Technology.

Topics: Study and practice fundamental topics in electrical and electronics engineering within 8 weeks (2 days per week). At the end, the students complete technical projects and present their projects to the evaluation committee.

Sponsors: by Faculty of Electrical and Electronics Engineering, Ho Chi Minh City University of Technology, and IEEE Vietnam Section.

<https://drive.google.com/file/d/1E3lnkj0ytKXJZ1zbHcmzgHJLqMSsgfiP/view?usp=sharing>

11. 2023 1st IEEE Asia Meeting on Environment and Electrical Engineering (2023 EEE-AM)

Date: 13-15 November 2023

Venue: Ha Noi, Vietnam

<https://eeeam.net/>

B.4 Students Activities

- Total number of Student Branches in the Section: 0
- Number of Student Branches formed in the current year: 0
- Section level student activities (student congress, paper and other contests, awards etc).
- Number of active Student Branches (Student Branches who have reported required number of meetings during the year): 0.

B.5 Affinity Group Activities

B.6 Awards & Recognition Activities

B.7 Communication Activities (Newsletter, Home Page, E-mail etc.)

B.8 Industry Relations

B.9 Humanitarian Technology Activities

B.10 Community Activities

PART C - OTHERS

C.1 Special Events

C.2 Relationship with National and International Societies and Non-Government Organizations (NGO)

C.3. Collaboration with other IEEE Sections

C.4 Support extended to Sub-sections & Society Chapters within the Section

C.5 Best Practices of your Section (which you would like to share with other Sections for the benefits of members)

C.6 Problems anticipated and suggestions for solutions, if any

PART D - GOALS AND PLANS

D.1 Continuation of project/activity in progress and their implementation plans

- Supporting professional and education activities such as conferences, technical seminars and lectures.
- Developing more student activities such as technical conferences/seminars, technical contests.
- Continuing further affinity group and community activities.
- Developing industry relations with activities such as membership development, industry sponsorship for professional and student activities, joint technical workshop/seminar between industry and academia.

D.2 Goals and Future Plans

Goals:

- Membership growth and retention for student grade and higher grade.
- Benefit to IEEE members in Vietnam Section.
- Developing industry relations.

Future plans:

- Developing more communication activities such as developing Vietnam Section homepage, broadcasting membership information to university and industry, connecting closely with Section members via Facebook/Viber.
- Developing benefit policy for IEEE Vietnam Section members.
- Besides supporting professional activities, developing and supporting more activities for student and industry.

D.3 Any innovative ideas to make IEEE more creative and value added for sustaining the membership retention and recruitment goals.

D.4 Business Plan for Sustainable Growth and Financial Stability.